



LG-T2727RGBA-TD-A DATA SHEET

 SPEC.NO.
 :
 SZ19081205

 DATE
 :
 2020/05/07

 REV.
 :
 A/1

Approved By:

Checked By:

Prepared By:

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LG-T2727RGBA-TD-A

TOP Full-color LED

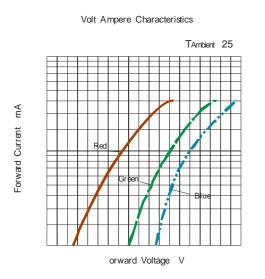


LIGHT ELECTRONICS CO., LTD.

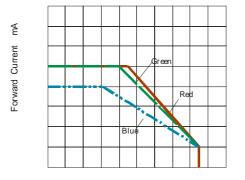


LIGHT ELECTRONICS CO., LTD.

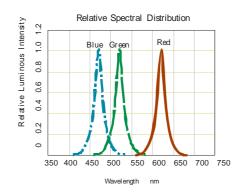




Forward Current Derating Curve



Ambient Temperature

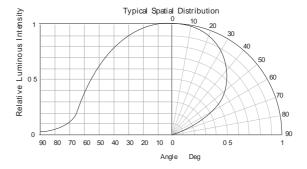




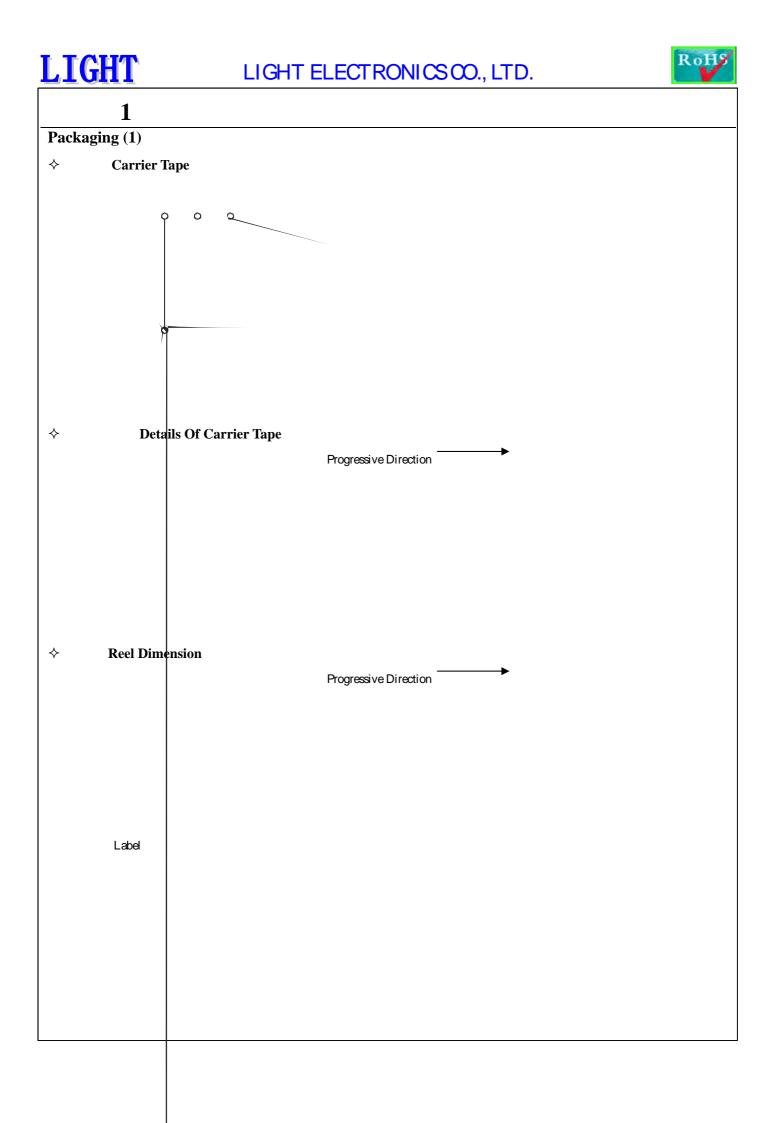


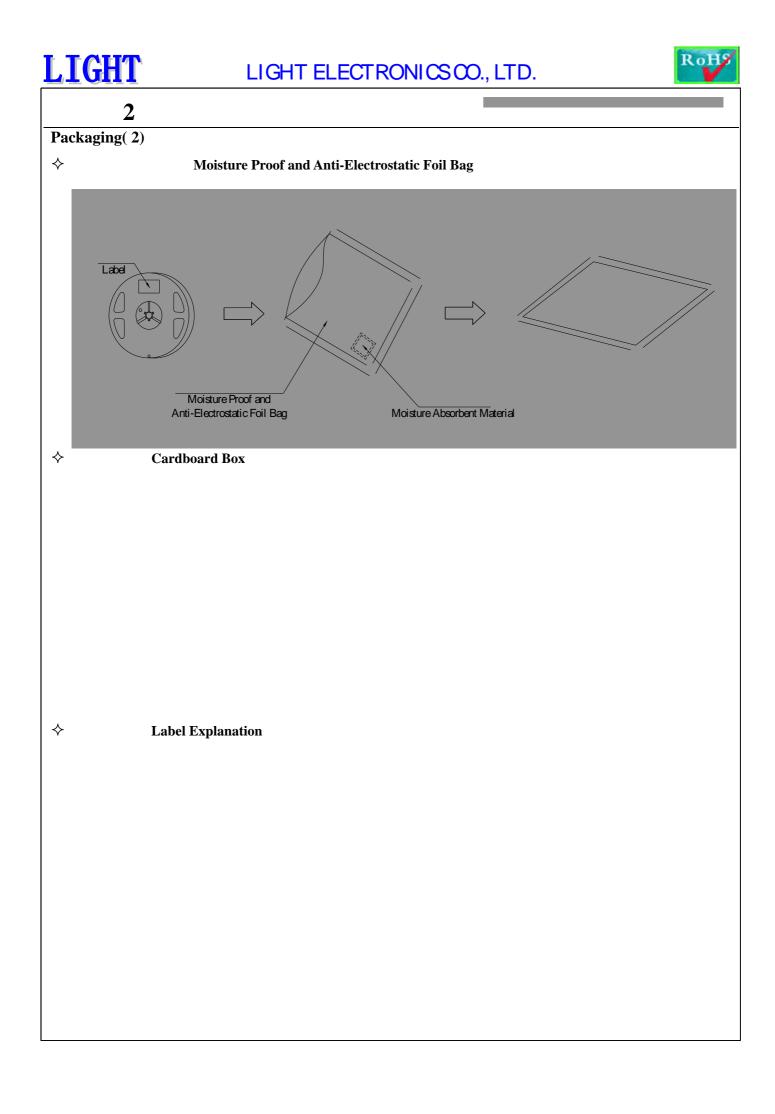
Relative Luminous Intensity

Forward Current mA









LIGHT	LIGHT ELECTRON	NICS CO., LTD.		RoHS
1				
Guideline for Soldering (1)			
1.				
Hand Soldering				
•	25	315		3
If manual soldering is the iron must be kep soldered at one time.	s used, the use of a soldering iror ot below 315 with soldering t SMD LED	n of less than 25W is recom ime within 3 seconds and		-
The energy regin of t		he tip of the coldering iron		
The epoxy resin of th	he SMD LED should not contact t	ne up or the soldering fron.		
 40 Handing of the SMI LED failures caused 2. 	s should be exerted on the resin po D LED should be done when the by thermal-mechanical stress in c	LEE e temperature of environmer condition of high temperature) nt is below 4 e.	0, in case of
1 260 250 217 200 150 150	#非温度想读者数 Recommended Solder Profile 所道 1-5℃/sec Ramp-up 1-5℃/sec <u>液集 Proheat</u> (60-120)sec.	10sec. no 10sec. no 60sec. no Rill 7C/sec Flamp-down 7C/ ne)	. BAX	0 of 13
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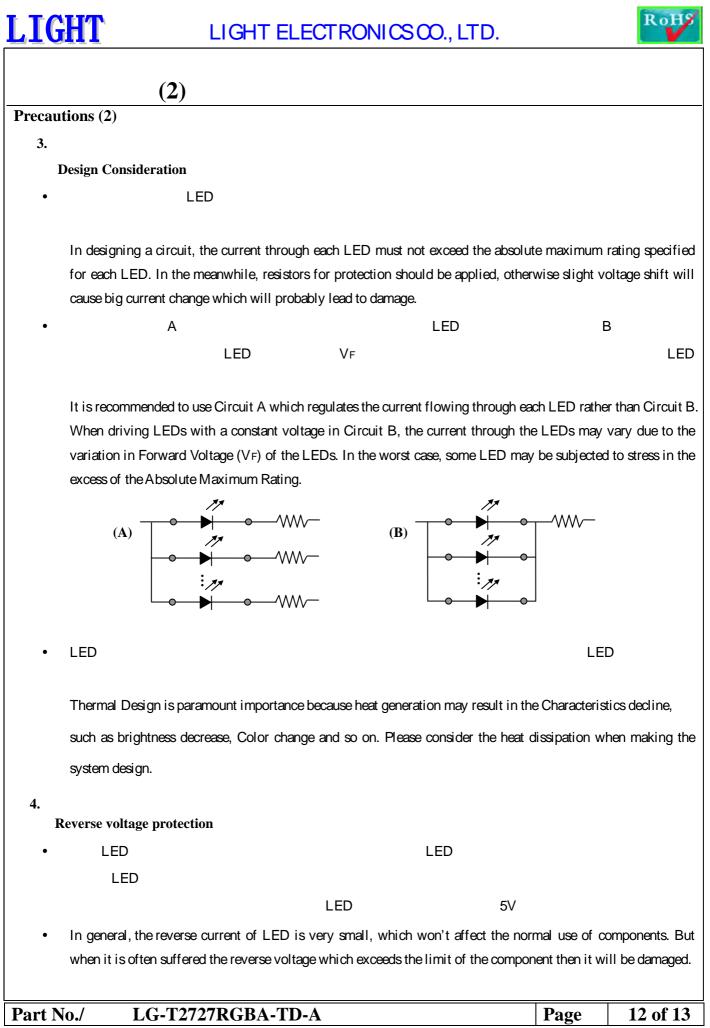
Guideline for Soldering (2)

Reflow soldering should not be done more than one time.

LED

Stress on the LEDs should be avoided during heating in the reflow soldering process.

LIGHT ELECTRONICS CO., LTD.
(1)
Precautions (1)
1.
Storage
 Moisture proof, anti-electrostatic package and moisture absorbent material are used, to keep moisture to a minimum. Humidity indicator card inside to test if the products are moisted. <30 <60 RH
Storage environment: All the products should be stored in the environment of temperature<30 and humidity<60 RH before foiled bags open and need to be baked before SMT.
Before using, please check whether there is any air leakage or not, If the bag has leaked air, Please bake the product with below condition.
• <30 <60 RH 12h
Before soldering ,the product must be stored under the condition of <30 and <60 RH. Under these conditions the SMD LEDs must be used (subject to reflow oven) within 12 hours. 70±5 12h 70±5 24h 6 70±5 48h Baking condition Within 2 months' storage undamped : 70±5 ×12h After 2 months' storage (undamped): 70±5 ×24h Damped/Foiled bag leakage/ beyond 6 months' storage at customers' side: 70±5 ×48h
Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs can not be lighted up. In view of the above, we should do some anti-static precautions when using the SMD LEDs.
All devices, equipments and machineries must be properly grounded, at the same time we should take measures to prevent anti-static and voltage surge.
It is also recommended that anti-electrostatic wrist bands, pads, uniforms, gloves or containers can be used when dealing with the LEDs.
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(3)

Precautions (3)

Such as the reverse current increase rapidly. And it will cause the string light when the screen is black. So please pay attention to controlling the reverse voltage which less than 5V is recommended.

5.

The safe temperature for LEDs working

LED

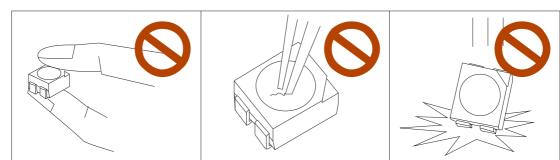
The high temperature will make the LEDs' Luminous Intensity decreased radically, if LEDs are used in hot environment for a long time, they will be disabled easily. When LEDs are used in a high density array, we suggest that the LEDs' surface temperature should be lower than 55 and the legs' temperature should be lower than 75.

55

6.

Others

When handling the product, touching the encapsulation with bare hands will not only contaminate its surface, but also have an effect on its optical characteristics. Excessive force to the encapsulation might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED

The epoxy resin of encapsulation is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.

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